

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Takeshi SAKAMOTO et al.

Application No.: 10/594,907

Confirmation No.: 8322

Filed: August 7, 2008

Art Unit: 2895

For: LASER PROCESSING METHOD FOR
CUTTING SUBSTRATE AND AND
LAMINATE PART BONDED TO THE
SUBSTRATE

Examiner: M. Jung

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION UNDER 37 C.F.R.

1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Madam:

INTRODUCTORY COMMENTS

In response to the non-final Office Action dated November 9, 2011, the period for response to which extends through April 9, 2012, by the concurrently filed request for a two-month extension of time and corresponding fee payment, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper; and

Remarks/Arguments begin on page 7 of this paper.